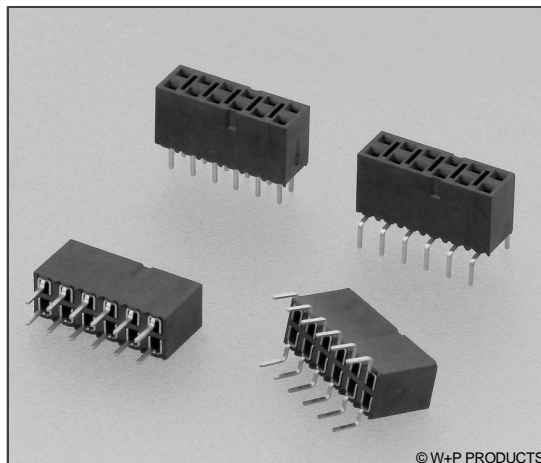


Buchsenleisten RM 2,54mm, gerade, 2-reihig – BH 7,3mm, durchsteckbar Female Headers, 2.54mm Pitch, Straight, Double Row – 7.3mm Profile, Pass Through

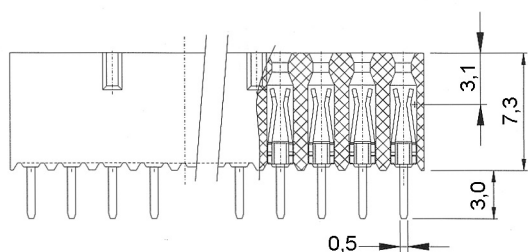
Technische Daten / Technical Data

| | |
|-----------------------|--|
| Isolierkörper | Thermoplast, nach UL94 V-0 |
| Insulator | Thermoplastic, rated UL94 V-0 |
| Kontaktmaterial | Kontakt für Vierkantstift 0,635mm, Kupferlegierung |
| Contact Material | Contact for square pin 0.635mm, copper alloy |
| Kontaktoberfläche | Lt. Oberflächenoptionen, über Ni (1,3 ... 2,5µm) |
| Contact Surface | Acc. to options (see below), over Ni (1.3 ... 2.5µm) |
| Durchgangswiderstand | < 20 mΩ |
| Contact Resistance | < 20 mΩ |
| Isolationswiderstand | > 1000 MΩ |
| Insulation Resistance | > 1000 MΩ |
| Spannungsfestigkeit | 500 V AC |
| Test Voltage | 500 V AC |
| Nennspannung | 250 V AC |
| Voltage Rating | 250 V AC |
| Nennstrom | 3 A |
| Current Rating | 3 A |
| Temperaturbereich | -40 °C ... +105 °C |
| Temperature Range | -40 °C ... +105 °C |
| Verarbeitung | Wellen- oder Reflow-Lötverfahren |
| Processing | Wave or reflow soldering |

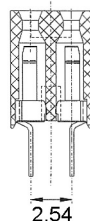


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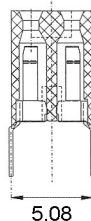
Doppelfederkontakte für Vierkantstifte 0,635mm.
Dual beam contacts accept 0.635mm square pins.



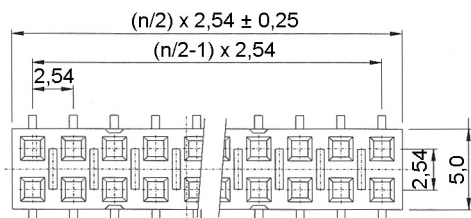
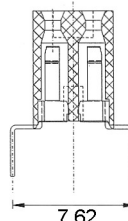
Layout 1



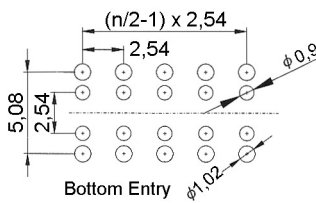
Layout 2



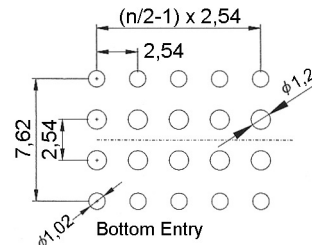
Layout 3



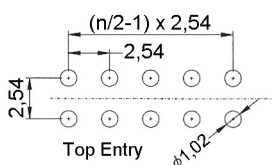
PCB-Layout



PCB-Layout



PCB-Layout



Series

349

Contacts*

04

04-80 Zweireihig
Double row

Layout*

1

1 2,54 x 2,54mm
2 2,54 x 5,08mm DIP spacing
3 2,54 x 7,62mm DIP spacing

Plating*

50

00 Vergoldet
Gold plated
50 Verzinkt
Tin plated
60 Sel. Au/Sn
Duplex plating

* Dies ist ein **Bestellbeispiel** - bitte durch Ihre Spezifikationen ersetzen.
* This is an **order example** - please replace by your specifications.

Informationen zum Wellen-Lötverfahren

Wave Soldering Information

Empfehlungen für das Wellenlötverfahren

Recommendations for Wave Soldering

Die Bauteile sollten bei einer Lötbadtemperatur von 260°C in max. 5 Sekunden verlötet werden.

Empfohlenes Wellenlötprofil:



Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

| Profileigenschaft | Kennwert |
|--------------------------------------|---------------|
| Temperatur Minimum T_{Smin} | 150 °C |
| Temperatur Maximum T_{Smax} | 200 °C |
| Dauer $T_{Smin} - T_{Smax}$ | 60 – 180s |
| Temperatur Lötbereich T_L | 217 °C |
| Verweildauer oberhalb T_L | 60 – 180s |
| Ramp-Up Rate $T_{Smax} - T_P$ | max. 3 °C / s |
| Höchsttemperatur T_P | 260±5 °C |
| Dauer Höchsttemperatur | 20 – 40s |
| Ramp-Down Rate $T_{Pmax} - T_{Smin}$ | 6 °C / s |
| Dauer 25 °C – Höchsttemperatur T_P | max. 8m |

Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

| Profile Feature | Key Values |
|--------------------------------------|---------------|
| Minimum Temperature T_{Smin} | 150 °C |
| Maximum Temperatur T_{Smax} | 200 °C |
| Duration $T_{Smin} - T_{Smax}$ | 60 – 180s |
| Soldering Range Temperature T_L | 217 °C |
| Duration above T_L | 60 – 180s |
| Ramp-Up Rate $T_{Smax} - T_P$ | max. 3 °C / s |
| Peak Temperature T_P | 260±5 °C |
| Duration Peak Temperature | 20 – 40s |
| Ramp-Down Rate $T_{Pmax} - T_{Smin}$ | 6 °C / s |
| Duration 25°C - Peak Temp. T_P | max. 8min |

